

Title (en)

BATH FOR THE ELECTROLYTIC DEPOSITION OF A GOLD ALLOY AND GALVANIC PROCESS USING THIS BATH

Publication

EP 0140832 B1 19880113 (FR)

Application

EP 84810428 A 19840830

Priority

CH 481283 A 19830901

Abstract (en)

[origin: EP0140832A2] 1. Electroplating bath for the electrolytic deposition of a gold-copper-cadiumzinc alloy, characterized in that it comprises a gold cyanide complex, a copper cyanide complex, a cadmium cyanide complex, an organic complexing agent capable of complexing the cadmium ions in the absence of free cyanide, a surfactant, and a mixture of zinc cyanide or copper cyanide and zinc-potassium cyanide, so constituted that the concentration of total cyanide bonded to the zinc is equal to from one to four times that of the zinc.

IPC 1-7

C25D 3/62

IPC 8 full level

C25D 3/62 (2006.01)

CPC (source: EP)

C25D 3/62 (2013.01)

Cited by

EP0193848A1; US4687557A; US6576114B1

Designated contracting state (EPC)

CH DE FR GB LI

DOCDB simple family (publication)

EP 0140832 A2 19850508; EP 0140832 A3 19850612; EP 0140832 B1 19880113; DE 3468704 D1 19880218

DOCDB simple family (application)

EP 84810428 A 19840830; DE 3468704 T 19840830